



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-04-20
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Giovanni Giacobello	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/online_tech_support.html">http://www.st.com/web/en/support/online_tech_support.html</a>		

**Uncertainty Statement**


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Legal Statement		
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>
		Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	B8V3*L693EA6	A	BO2A	2015-04-20
Amount	UoM	Unit type	ST ECOPACK Grade	
5592.00	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	20 - 10.7 - 4.5	15	Through-hole	
Comment	Package: MULTIWATT 15L IN LINE; MDF valid for L298HN			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BSV3*L693EA6						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
die (s)	Other inorganic materials	6.834	mg	supplier	die	Silicon (Si)	7440-21-3		6.681	mg	977612	1195	
die (s)				supplier	metallization	Aluminum (Al)	7429-90-5		0.082	mg	11999	15	
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.028	mg	4097	5	
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.037	mg	5414	7	
die (s)				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.001	mg	146	0	
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	146	0	
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.004	mg	585	1	
Leadframe	Copper & its alloys	3092.56	mg	supplier	alloy	Copper (Cu)	7440-50-8		3083.718	mg	997141	551452	
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		1.42	mg	459	254	
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		2.594	mg	839	464	
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		4.828	mg	1561	863	
Soft solder	Solder	5.126	mg	JIG Table A	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	4.998	mg	975029	894	
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.077	mg	15021	14	
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.051	mg	9949	9	
Bonding wire	Other inorganic materials	1.884	mg	supplier	wire	Copper (Cu)	7440-50-8		1.884	mg	1000000	337	
encapsulation	Other inorganic materials	2463.626	mg	supplier	mold compound	Silica, vitreous	60676-86-0		1766.42	mg	717000	315883	
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		418.816	mg	170000	74896	
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		177.381	mg	72000	31720	
encapsulation				JIG I	mold compound	Brominated epoxy resin	40039-93-8		36.955	mg	15000	6609	
encapsulation				supplier	mold compound	Bismuth	7440-69-9		7.391	mg	3000	1322	
encapsulation				supplier	mold compound	Carbon black	1333-86-4		7.391	mg	3000	1322	
encapsulation				supplier	mold compound	Antimony Trioxide	1309-64-4		49.272	mg	20000	8811	
connections coating	Solder	21.97	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		21.97	mg	1000000	3929	